

Claim 2 (Canceled).

3. (Original) A circuit board according to Claim 1, wherein said soldering bump contains tin, silver and copper.

4. (Previously Amended) A circuit board according to Claim 1, wherein said circuit board is a circuit provided suspension substrate.

5. (Previously Amended) A connection structure for connecting a terminal portion of a circuit board with an external terminal formed in an external circuit, wherein said terminal portion is provided with a nickel plating layer and a soldering bump provided on said terminal portion and a thickness of said nickel plating layer is within a range of 1.0 to 4.0 μm , and wherein said terminal portion is further provided with a base layer and a conductive layer, which is disposed between said base layer and said nickel plating layer, and wherein said base layer comprises polyimide resin.

6. (Previously Added) The circuit board according to claim 1, wherein a thickness of the base layer is 2-30 μm .

7. (Previously Added) The circuit board according to claim 1, wherein a thickness of the conductive layer is 3-25 μm .

8. (Previously Added) The circuit board according to claim 1, wherein the terminal portion further includes a cover layer disposed on said base layer, having a thickness of .5 - 8.0 μm .

9. (Previously Added) The circuit board according to claim 3, wherein a composition ratio of said soldering bump is 95-97% by weight of said tin, 0-4% by weight of said silver, and 0-4% by weight of said copper.

10. (New) The circuit board according to claim 1, wherein a composition ratio of said soldering bump is 0.3 - 3.5 % by weight of said silver.

11. (New) The circuit board according to claim 1, wherein a composition ratio of said soldering bump is 0.2 - 1.2 % by weight of said copper.